

A

B

C

D

E

版次	ECN 編號	描述	設計/日期
12	ECR-5A0064	修改尺寸規範 (改為2.45±0.10)	馬花春_10/22'05
13	CW08090034	變更新格式發行	唐亮_09/16'08
14	PH14070068	根據規格書修正電流為0.5A	張浩_07/16'14

Recommended PCB Layout
(PCB TOLERANCE ±0.05)

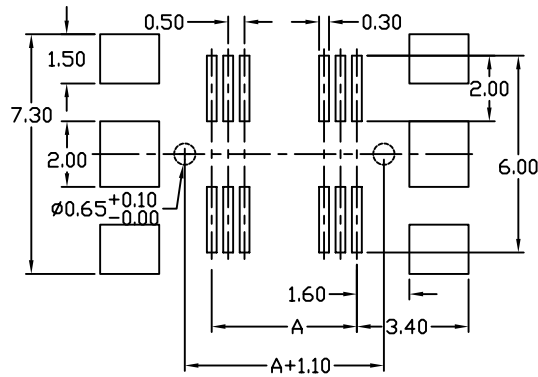
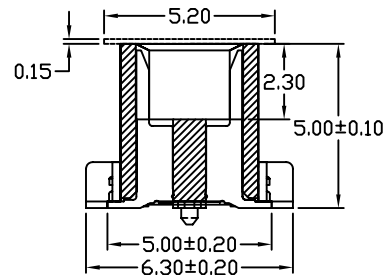
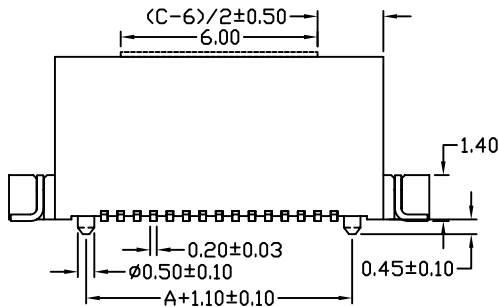
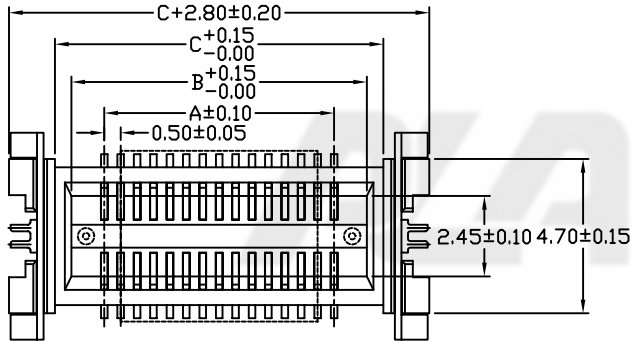


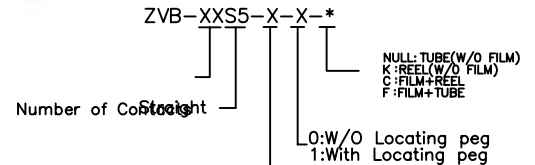
Diagram	Molding description
○	mass production & assemble mold
⊙	sample & assemble mold
⊕	mass production & fix mold
⊗	sample & fix mold

No. of con.	DIM A	DIM B	DIM C	(res)	(amp)
10	2.00	4.00	5.00	●	
12	2.50	4.50	5.50	●	
14	3.00	5.00	6.00	●	
16	3.50	5.50	6.50	●	
18	4.00	6.00	7.00	●	
20	4.50	6.50	7.50	●	
22	5.00	7.00	8.00	●	
24	5.50	7.50	8.50	●	
26	6.00	8.00	9.00	●	
28	6.50	8.50	9.50	●	
30	7.00	9.00	10.00	⊕	
32	7.50	9.50	10.50	●	
34	8.00	10.00	11.00	●	
36	8.50	10.50	11.50	⊕	
38	9.00	11.00	12.00	●	
40	9.50	11.50	12.50	⊕	
42	10.00	12.00	13.00	●	
44	10.50	12.50	13.50	●	
46	11.00	13.00	14.00	●	
48	11.50	13.50	14.50	●	
50	12.00	14.00	15.00	⊕	
52	12.50	14.50	15.50	●	
54	13.00	15.00	16.00	●	
56	13.50	15.50	16.50	●	
58	14.00	16.00	17.00	●	
60	14.50	16.50	17.50	●	
62	15.00	17.00	18.00	●	
64	15.50	17.50	18.50	●	
66	16.00	18.00	19.00	●	
68	16.50	18.50	19.50	●	
70	17.00	19.00	20.00	⊕	
72	17.50	19.50	20.50	●	
74	18.00	20.00	21.00	●	
76	18.50	20.50	21.50	●	
78	19.00	21.00	22.00	●	
80	19.50	21.50	22.50	●	
82	20.00	22.00	23.00	●	
84	20.50	22.50	23.50	●	
86	21.00	23.00	24.00	●	
88	21.50	23.50	24.50	●	
90	22.00	24.00	25.00	●	
92	22.50	24.50	25.50	●	
94	23.00	25.00	26.00	●	
96	23.50	25.50	26.50	●	
98	24.00	26.00	27.00	●	
A0(100)	24.50	26.50	27.50	●	
A2(102)	25.00	27.00	28.00	●	
A4(104)	25.50	27.50	28.50	●	
A6(106)	26.00	28.00	29.00	●	
A8(108)	26.50	28.50	29.50	●	
B0(110)	27.00	29.00	30.00	●	
B2(112)	27.50	29.50	30.50	●	
B4(114)	28.00	30.00	31.00	●	
B6(116)	28.50	30.50	31.50	●	
B8(118)	29.00	31.00	32.00	●	
C0(120)	29.50	31.50	32.50	●	



NOTES: (UNLESS OTHERWISE SPECIFIED)

1. CURRENT RATING: 0.5 AMPERE.
2. CONTACT RESISTANCE: 60 m ohms MAX. FOR INITIAL.
3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms. PER ONE MINUTE.
4. INSULATION RESISTANCE: 100 M ohms MIN..
5. HARMFUL MATERIAL SHOULD BE COMPLIANT TO DOC. "EI-0005" STANDARDS.
6. PRODUCT NUMBER MATRIX:



Contact Plating

Definition	Code
◎ Gold plated:	
flash	B 15μ" F
10μ"	E 30μ" J
◎Standard: B	All plating is lead free



一般公差		比例:	設計:	日期:	圖號:	名稱:	版次:
XX. ±0.50	XXX.* ±	1:1	JOHNSON	07/16'14	600-0000-0560	CUSTOMER DRAWING	14
X. ±0.30	.XXX.* ± 0.10	單位:	審核:	日期:	零件系列:	0.5P, Board To Board	頁次:
.X ±0.25	X.* ± 4°	尺寸:	核准:	日期:	ZVB-XXS5-X-X-*	SOCKET type	1/1
.XX ±0.20	.X.* ± 4°	A4	CHANGGUI_CHEN	07/16'14			

A

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C

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